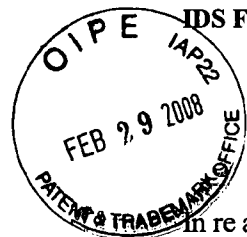


Form PTO-1449  
U.S. Application No.: 10/725,933  
Attorney Docket No.: HK9225US  
IDS Filed: February 26, 2008



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INFORMATION DISCLOSURE CITATION

In re application of: Yang et al.

Confirmation No.: 4487

Serial No.: 10/725,933

Group No.: 2891

Filed: December 3, 2003

Examiner: David A. Zarneke

For: FAN OUT TYPE WAFER LEVEL PACKAGE STRUCTURE AND METHOD OF THE SAME

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Other Documents (Inc. Author, Title, Date, Pertinent Pages, Etc.)**Examiner**

<b>Initials</b>	<b>Document</b>
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_____	Yuan et al., "Design, Experiment and Analysis of the Solder on Rubber (SOR) Structure of WLCSP, 7 <sup>th</sup> Int. Conf. on Thermal, Mechanical and Multiphysics Simulation and Experiments in Micro-Electronics and Micro-Systems, EuroSimE 2006.
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**Examiner:****Date Considered:**\_\_\_\_\_  
/David Zarneke/\_\_\_\_\_  
06/07/2008

**\*\*Examiner:** Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.